

CATALOG

Shenzhen Minder Semiconductor Co., Limited



Shenzhen Minder Semiconductor Co., Limited
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● Company Profile

Shenzhen Minder Semiconductor Co., Limited

Minder is an integrated provider of storage product solutions, encompassing R&D, production and sales. We specialize in the design and manufacturing of products such as eMMC, SSDs and portable solid-state drives. Committed to laying a solid data foundation for the intelligent world, our vision is to become a global leader in the storage industry, guided by our core values of "Innovation Leads, Excellence Drives."

Total Facility Area

10,000 m²

Total Value of Equipment

100 Million RMB

Monthly Production Capacity

800 K

Annual Output Value

2 Billion+ RMB

Number of Patent Applications

75

● Corporate Culture Measured by Excellence, Define Tomorrow.

Vision & Pattern

Vision & Perspective: We monitor the industry with a holistic mindset—strategic in foresight, pragmatic in precision.

Quality & Brand

We hold quality as our paramount principle and brand as our foundation, ensuring that the pursuit of "Extreme Excellence" permeates every detail of R&D, production and service.

Management & Talent

We implement an efficient and transparent flat management structure, promoting fair competition where merit is recognized and rewarded. We treat everyone equally and recognize individualism; we allow room for growth and never tolerate complacency. Our commitment is to provide a stage where dedicated individuals can fully realize their potential.

Our Workplace & Events





● Manufacturing Capabilities

We have established a complete closed-loop production process, spanning from wafer grinding and dicing to chip packaging and testing, all the way through to SSD assembly and final verification. Our capabilities are anchored in a modern manufacturing facility exceeding 10,000 square meters, equipped with 8 SMT lines. This infrastructure enables a monthly production capacity of 800K units, forming a robust and vertically integrated manufacturing system.

Die Sorting



NAND Sorting



Die Bonding



SMT



Wire Bonding



RDY and BIT



Molding



Singulation



Assembly



● Core Competencies



Full-Industry-Chain Vertical Integration & Autonomous Control

We are far more than an assembly plant. We have achieved the rare feat of establishing a complete closed-loop industrial chain—encompassing wafer grinding, packaging and testing, SMT mounting, and final product testing. This allows us to break free from relying on external production companies and technology, retaining full control over every step in our product lifecycle.



Dual Superiority in Both Cost and Quality

Leveraging direct access to upstream core resources and highly efficient internal supply chain coordination, we build unparalleled cost competitiveness within the industry. Furthermore, our end-to-end in-house production allows us to implement a quality control system that far exceeds industry standards, achieving the seemingly paradoxical goal of **"Premium Quality, Accessible Cost."**



Strong Market Resilience and Rapid Demand Response

During industry fluctuations or shortage crises, our upstream resources ensure supply stability, while our in-house production capacity guarantees absolute delivery flexibility. This dual advantage of **"Secured Resources + Agile Capacity"** enables us to cope with market changes with confidence and provide our customers with the fastest and most stable supply assurance.



Sustained Leadership Driven by Technology and Capital as Dual Engines

Our robust capital strength provides sustained fuel for up-front R&D, while our deep-seated technical expertise ensures we can rapidly translate market insights into industry-defining benchmark products. This drives our evolution from **"Following the Market"** to actively **"Defining the Market."**

● Awards & Certifications

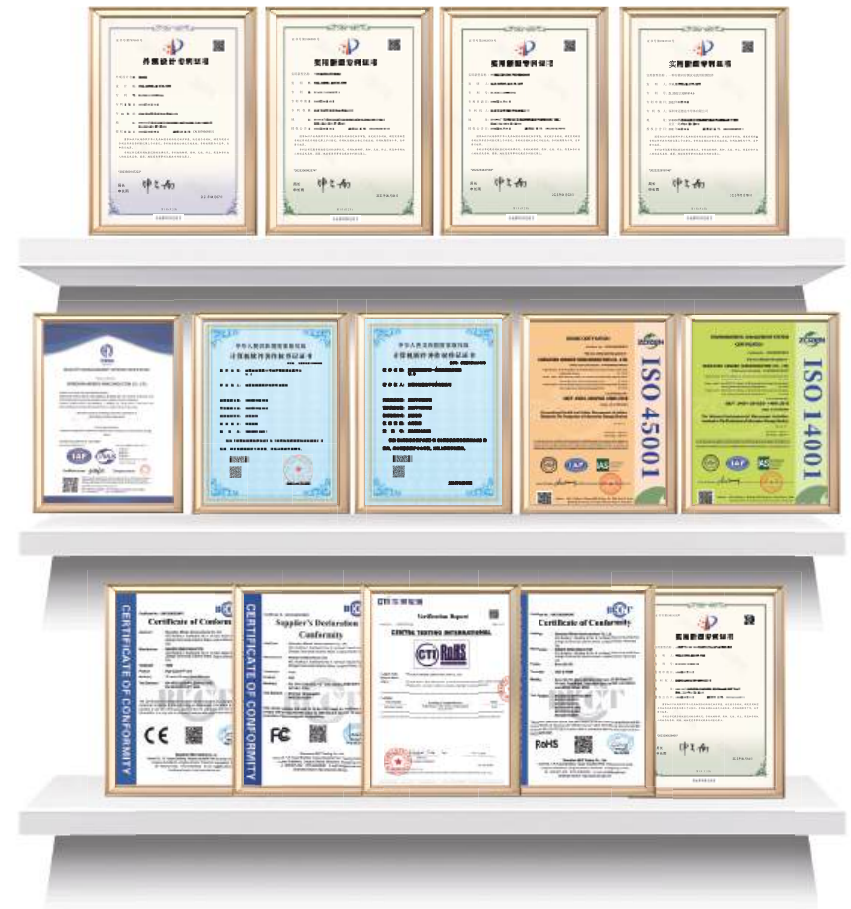
We have been recognized with multiple honors and certifications, including:

- Selected for the "Specialized, Refined, Unique and New" Enterprise List (Shenzhen)
- Specialized, Sophisticated, Differentiated and Innovative Enterprise (Shenzhen)
- National High-Tech Enterprise
- Innovative SME (Shenzhen)
- National Technology-based SME
- Member of the Guangdong Semiconductor Industry Association



● Intellectual Property (IP)

As of 2025, the company has filed 75 patent applications, with over 25 patents granted.



● Global Presence



Embedded Storage

eMMC 5.1

■ Features

- Supports LDPC ECC Algorithm for Robust Data Protection.
- Incorporates Wear-Leveling Technology to Significantly Extend Product Lifespan.
- Ensures High Reliability and Broad Compatibility Through Rigorous Testing.
- Offers Comprehensive Customization (Software/Hardware) and Services (Pre-Sales/After-Sales Support, Custom Validation Testing).
- 1-Year Warranty, Commercial-Grade Quality With a Failure Rate ≤ 20 PPM.



■ Specification

Series	Apex
P/N	TEMXXC032
Interface	eMMC 5.1 standard, backward compatible, JEDEC Standards Compliant, Support HS400
Capacity	TLC: 32GB, 64GB, 128GB, QLC: 256GB
Encapsulation	BGA153
Dimension	11.5×13×1.0mm
Working Voltage	VCC=3.3V(2.7V~3.6V), VCCQ=1.8V(1.7V~1.95V)
Seq Read/Write	Up to 320/200MB/s
4K Random Read/Write	Up to 3.5K/4K IOPS
Operating Temp.	Commercial regulations: -20°C~80°C
Reliability	Data retention period: >10 years, durability: TLC (3K P/E cycles)
Supported Features	Write protection, hardware reset, background operation, secure erase

■ Test Environment



■ Applications



■ Features

- Supports LDPC ECC Algorithm for Robust Data Protection.
- Incorporates Wear-Leveling Technology to Significantly Extend Product Lifespan.
- Ensures High Reliability and Broad Compatibility Through Rigorous Testing.
- Offers Comprehensive Customization (Software/Hardware) and Services (Pre-Sales/After-Sales Support, Custom Validation Testing).
- 1-Year Warranty, Commercial-Grade Quality With a Failure Rate ≤ 20 PPM.



■ Specification

Series	Apex
P/N	TEMXXC008
Interface	eMMC 5.1 standard, backward compatible, JEDEC Standards Compliant, Support HS400
Capacity	MLC: 4GB, 8GB, 16GB, 32GB
Encapsulation	BGA153
Dimension	11.5×13×1.0mm
Working Voltage	VCC=3.3V(2.7V~3.6V), VCCQ=1.8V(1.7V~1.95V)
Seq Read/Write	Up to 230/210MB/s
4K Random Read/Write	Up to 3.6K/1.8K IOPS
Operating Temp.	Commercial regulations: -20°C~80°C
Reliability	Data retention period: >10 years, durability: MLC (5K P/E cycles)
Supported Features	Write protection, hardware reset, background operation, secure erase

■ Test Environment



■ Applications



Solid-State Drive

M.2 PCIe 5.0

Advantages

- Peak Performance, Breaking Transmission Bottlenecks
- Designed for Future Platforms
- Professional-Grade Reliability

Features

- Sequential Read/Write Speeds Exceed 14,000/13,000 MB/s
- Ultra-Low Latency & Extreme Bandwidth
- Advanced Power Management & Thermal

Specification

Series	Promethean
P/N	TME58SDXXX
Interface	M.2 M Key connector, PCIe Gen5×4, NVMe 2.0
Capacity	512GB, 1TB, 2TB, 4TB
NAND	3D NAND
Seq Read/Write	Up to 14,000/13,000MB/s
4K Random Read/Write	Up to 1,500K/1,200K IOPS
Dimension(LxWxH)	22×80×2.2mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Durability(TBW)	512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW, 4TB: 1920TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)



Applications



High-End Gaming
Consoles / PCs



Extreme Overclocking
Platforms



HPC Clusters



8K Real-Time
Video Editing



Data Center
Edge Nodes

Advantages

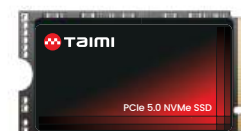
- Peak Performance, Breaking Transmission Bottlenecks
- Designed for Future Platforms
- Professional-Grade Reliability

Features

- Sequential Read/Write Speeds Exceed 14,000/13,000 MB/s
- Ultra-Low Latency & Extreme Bandwidth
- Advanced Power Management & Thermal

Specification

Series	Promethean
P/N	TME54SDXXX
Interface	M.2 M Key connector , PCIe Gen5×4 , NVMe 2.0
Capacity	512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 14,000/13,000MB/s
4K Random Read/Write	Up to 1,500K/1,200K IOPS
Dimension(LxWxH)	22×42×2.2mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Durability(TBW)	512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)



Applications



High-End Gaming
Consoles / PCs



Extreme Overclocking
Platforms



HPC Clusters



8K Real-Time
Video Editing



Data Center
Edge Nodes

Solid-State Drive

M.2 PCIe 4.0

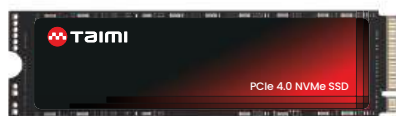


Advantages

- The Prime Choice for Current High-End Configurations
- Ideal for 4K/8K Video Editing & Large-Scale Rendering
- Strong Future Compatibility / Forward-Compatible Design

Features

- Sequential Read/Write Speeds up to 7,000/6,000 MB/s
- Exceptional Random Read/Write Performance
- Supports Advanced ECC & LDPC Error Correction



Specification

Series	Phoenix
P/N	TME48SBXXX
Interface	M.2 M Key connector, PCIe Gen4×4, NVMe 1.4
Capacity	256GB, 512GB, 1TB, 2TB, 4TB
NAND	3D NAND
Seq Read/Write	Up to 7,000/6000MB/s
4K Random Read/Write	Up to 1,000K/900K IOPS
Dimension(LxWxH)	22×80×2.2 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW, 4TB: 1920TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	Support advanced LDPC error correction, SLC cache acceleration, end-to-end data protection

Applications



Advantages

- The Prime Choice for Current High-End Configurations
- Ideal for 4K/8K Video Editing & Large-Scale Rendering
- Strong Future Compatibility / Forward-Compatible Design

Features

- Sequential Read/Write Speeds up to 7,000/6,000 MB/s
- Exceptional Random Read/Write Performance
- Supports Advanced ECC & LDPC Error Correction



Specification

Series	Phoenix
P/N	TME44SBXXX
Interface	M.2 M Key connector, PCIe Gen4×4, NVMe 1.4
Capacity	256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 7,000/6000MB/s
4K Random Read/Write	Up to 1,000K/900K IOPS
Dimension(LxWxH)	22×42×2.2 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	Support advanced LDPC error correction, SLC cache acceleration, end-to-end data protection

Applications



Solid-State Drive

M.2 PCIe 3.0



Advantages

- Powerful Performance with Extreme Responsiveness
- High Energy Efficiency with Excellent Power Control
- Broad Compatibility with Mainstream Platforms

Features

- Sequential Read/Write Speeds up to 3,000/2,900 MB/s
- Ultra-Low Latency & High IOPS
- Supports Dynamic Thermal Management



Specification

Series	Vulcan
P/N	TME38MBXXX
Interface	M.2 M Key connector, PCIe Gen3×4, NVMe 1.4
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 3,000/2,900MB/s
4K Random Read/Write	Up to 600K/550K IOPS
Dimension(LxWxH)	22×80×2.2 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Esports Gaming Laptops



Desktop PCs



HPC



Data Analysis

Advantages

- Powerful Performance with Extreme Responsiveness
- High Energy Efficiency with Excellent Power Control
- Broad Compatibility with Mainstream Platforms

Features

- Sequential Read/Write Speeds up to 3,000/2,900 MB/s
- Ultra-Low Latency & High IOPS
- Supports Dynamic Thermal Management



Specification

Series	Vulcan
P/N	TME34MBXXX
Interface	M.2 M Key connector, PCIe Gen3×4, NVMe 1.4
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 3,000/2,900MB/s
4K Random Read/Write	Up to 600K/550K IOPS
Dimension(LxWxH)	22×42×2.2 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Esports Gaming Laptops



Desktop PCs



HPC



Data Analysis

Solid-State Drive

M.2 SATA



Advantages

- High Stability & Low Heat Generation
- Easy to Install, Plug and Play
- High Cost-Effective SATA Solution

Features

- Continuous Read and Write Speed up to 550/500 MB/s
- Supports SATA III 6Gb/s
- No Moving Parts, Anti Vibration



Specification

Series	Solara
P/N	TM2S8SAXXX
Interface	M.2 B&M Key connector, SATAIII 6Gb/s protocol
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
Dimension(LxWxH)	22×80×2.2 mm
Working Voltage	3.3V ±5%
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
MTBF	>1,000,000 hours
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	Supports TRIM, S.M.A.R.T., NCQ

Applications



Advantages

- High Stability & Low Heat Generation
- Easy to Install, Plug and Play
- High Cost-Effective SATA Solution

Features

- Continuous Read and Write Speed up to 550/500 MB/s
- Supports SATA III 6Gb/s
- No Moving Parts, Anti Vibration



Specification

Series	Solara
P/N	TM2S4SAXXX
Interface	M.2 B&M Key connector, SATAIII 6Gb/s protocol
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
Dimension(LxWxH)	22×42×2.2 mm
Working Voltage	3.3V ±5%
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	28GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
MTBF	>1,000,000 hours
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	Supports TRIM, S.M.A.R.T., NCQ

Applications



Solid-State Drive mSATA



Advantages

- Compact & Thin, Space-Saving
- Ideal for Space-Constrained Applications
- High Stability & Low Heat Generation

Features

- Read/Write Speeds up to 550/500 MB/s
- Low Latency, Fast Response
- Supports DEVSLP (Device Sleep) Power-Saving Mode



Specification

Series	Helios
P/N	TMSATSXXX
Interface	mSATA(based on SATAIII 6Gb/s protocol)
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
4K Random Read/Write	Up to 85k/75K IOPS
Dimension(LxWxH)	50.8×29.85×3.85 mm
Working Voltage	3.3V ±5%
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB:70TBW, 256GB:140TBW, 512GB:240TBW, 1TB:480TBW, 2TB:960TBW
Seismic Resistance	1500G/0.5ms during operation, 5000G during non operation
MTBF	>1,000,000 hours
Warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Industrial Computers



Thin Clients



Mini PCs



Digital Signage

Advantages

- Compact & Thin, Space-Saving
- Ideal for Space-Constrained Applications
- High Stability & Low Heat Generation

Features

- Read/Write Speeds up to 550/500 MB/s
- Low Latency, Fast Response
- Supports DEVSLP (Device Sleep) Power-Saving Mode



Specification

Series	Helios
P/N	TMSATMAXXX
Interface	mSATA(based on SATAIII 6Gb/s protocol)
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
4K Random Read/Write	Up to 85k/75K IOPS
Dimension(LxWxH)	50.8×29.85×3.85 mm
Working Voltage	3.3V ±5%
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB:70TBW, 256GB:140TBW, 512GB:240TBW, 1TB:480TBW, 2TB:960TBW
Seismic Resistance	1500G/0.5ms during operation, 5000G during non operation
MTBF	>1,000,000 hours
Warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Industrial Computers



Thin Clients



Mini PCs



Digital Signage

Solid-State Drive

2.5" SATA



Advantages

- Broad Compatibility & Plug-and-Play
- Cost-Effective, Ideal for Storage Upgrades
- High Durability for Long-Term Stable Operation

Features

- Sequential Read/Write Speeds up to 550/500 MB/s
- Supports SATA III 6Gb/s High-Speed Interface
- Features Low Power Consumption & Silent Operation

Specification

Series	Aurora
P/N	TSA25SAXXX
Interface	SATAIII 6Gb/s, Compatible with SATA II/I
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
4K Random Read/Write	Up to 90K/80K IOPS
Dimension(LxWxH)	100.0×69.9×7.0 mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	TRIM, S.M.A.R.T., Garbage recycling, wear leveling

Applications



Legacy Computer Upgrade



Office & Home PCs



Desktop Storage Expansion



External Storage Enclosures



Surveillance Storage

Advantages

- Broad Compatibility & Plug-and-Play
- Cost-Effective, Ideal for Storage Upgrades
- High Durability for Long-Term Stable Operation

Features

- Sequential Read/Write Speeds up to 550/500 MB/s
- Supports SATA III 6Gb/s High-Speed Interface
- Features Low Power Consumption & Silent Operation

Specification

Series	Aurora
P/N	TSA25MAXXX
Interface	SATAIII 6Gb/s, Compatible with SATA II/I
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
4K Random Read/Write	Up to 90K/80K IOPS
Dimension(LxWxH)	100.0×69.9×7.0 mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)
Supported Features	TRIM, S.M.A.R.T., Garbage recycling, wear leveling

Applications



Legacy Computer Upgrade



Office & Home PCs



Desktop Storage Expansion



External Storage Enclosures



Surveillance Storage

Solid-State Drive Portable SSD

Advantages

- Extreme Portability & Compatibility
- Exceptional Durability & Protection
- Reliable & Durable

Features

- Quiet Operation, Low Temperature & Sustained Stability
- Premium Metal Housing for High-End Feel & Reliable Protection
- Large Capacity from 128GB to 2TB

Specification

Series	Beacon
P/N	TPSSDSCXXX
Interface	SATAIII 6Gb/s, Compatible with SATA II/I
Capacity	128GB, 256GB, 512GB, 1TB, 2TB
NAND	3D NAND
Seq Read/Write	Up to 550/500MB/s
4K Random Read/Write	Up to 90K/80K IOPS
Dimension(LxWxH)	60x17x10mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Durability(TBW)	128GB: 70TBW, 256GB: 140TBW, 512GB: 240TBW, 1TB: 480TBW, 2TB: 960TBW
Warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Smartphones



Tablets



Desktop PCs



Memory Card

CF Express Card



Advantages

- Essential for Professional Imaging Equipment
- High Reliability with Ensured Data Security
- Compatible with XQD Devices (via Adapter)

Features

- Read/Write Speeds up to 3,500/2,800 MB/s
- Supports Continuous 4K/8K RAW Video Recording
- High-Strength Durable Design



Specification

Series	Blitz
P/N	TCFEHTBXXX
Interface/Protocol	CF express Type B appearance, PCIe Gen4 × 2, NVMe 1.0 protocol
Capacity	256GB, 512GB, 1TB, 2TB, 4TB
Seq Read/Write	Up to 3,500/2,800MB/s
Dimensions (LxWxH)	38.5×29.6×3.8 mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Protective Performance	Shock resistant, impact resistant, X-ray resistant, magnetic resistant, and temperature resistant
Compatibility	Fully compatible with CFexpress Type B slot devices, can be used on USB 3.2 Gen2 × 2 interface through a card reader
warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Professional Camcorders



Cinema Cameras



High-Speed Burst Photography

Advantages

- Essential for Professional Imaging Equipment
- High Reliability with Ensured Data Security
- Compatible with XQD Devices (via Adapter)

Features

- Read/Write Speeds up to 1,700/1,650 MB/s
- Supports Continuous 4K/8K RAW Video Recording
- High-Strength Durable Design



Specification

Series	Nova
P/N	TCFELTXXX
Interface/Protocol	CF express Type B appearance, PCIe Gen3 x2, NVMe 1.0 protocol
Capacity	256GB, 512GB, 1TB
Seq Read/Write	Up to 1,700/1,650MB/s
Dimensions (LxWxH)	38.5×29.6×3.8 mm
Operating Temp.	0°C-70°C
Storage Temp.	-40°C-85°C
Protective Performance	Shock resistant, impact resistant, X-ray resistant, magnetic resistant, and temperature resistant
Compatibility	Fully compatible with CFexpress Type B slot devices, can be used on USB 3.2 Gen2 × 2 interface through a card reader
warranty	3 years or corresponding TBW restrictions (whichever comes first)

Applications



Professional Camcorders



Cinema Cameras



High-Speed Burst Photography

Memory Card

SD Card

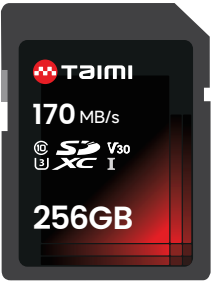


Advantages

- Compact Size & Versatile Applications
- Cost-Effective with Multiple Capacity Options
- Reliable, Durable & Suited for Harsh Conditions

Features

- Compliant with UHS-I Standard
- U3, V30, A2 – Speed Class U3, V30 & A2
- Waterproof, Shockproof & Temperature Resistant



Specification

Series	Flicker
P/N	TMSHRASXXX
Interface/Protocol	SD card, compliant with SD Association standards
Capacity/Type	SDXC: 64GB, 128GB, 256GB
Speed Rating	High performance series: UHS-I, U3, V30, A2
Seq Read/Write	Up to 170/150MB/s
Dimensions(LxWxH)	32x24x2.1 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Protection Level	Waterproof (IPX8), heat-resistant, impact resistant, and X-ray resistant (compliant with IEC/EN 529 standards)
Application Performance Level	A2(4,000/2,000 IOPS)
Warranty	10-year limited warranty

Applications



Memory Card

Micro SD Card

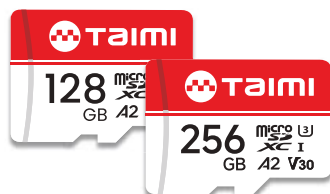


Advantages

- Compact Size & Wide Compatibility
- Cost-Effective with Multiple Capacity Options
- Reliable, Durable & Suited for Demanding Conditions

Features

- Compliant with UHS-I Standard
- Speed Ratings: U3, V30, A2
- Waterproof, Shockproof & Temperature Resistant



Specification

Series	Summit
P/N	TMSHRASXXX
Interface/Protocol	Micro SD (TF) card, compliant with SD Association specifications
Capacity/Type	Micro SD XC: 64GB, 128GB, 256GB
Speed Rating	High performance series: UHS-I, U3, V30, A2
Seq Read/Write	Up to 180/150MB/s
Dimensions(LxWxH)	15.0x11.0x1.0 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Protection Level	Waterproof (IPX8), heat-resistant, impact resistant, and X-ray resistant (compliant with IEC/EN 529 standards)
Application Performance Level	A2(4,000/2,000 IOPS)
Warranty	10-year limited warranty

Applications



Smartphones



Dash Cams



Drones



Action
Cameras



Surveillance
Systems



Portable Gaming
Devices



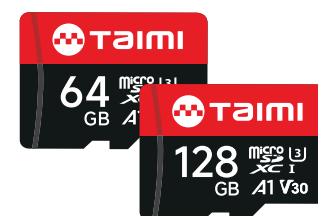
Camera
Gimbals

Advantages

- Compact Size & Wide Compatibility
- Cost-Effective with Multiple Capacity Options
- Reliable, Durable & Suited for Demanding Conditions

Features

- Compliant with UHS-I Standard
- Speed Ratings: U3, V30, A1
- Waterproof, Shockproof & Temperature Resistant



Specification

Series	Ember
P/N	TMSLBAIXXX
Interface/Protocol	Micro SD (TF) card, compliant with SD Association specifications
Capacity/Type	Micro SD XC/Micro SD HC: 32GB, 64GB, 128GB, 256GB
Speed Rating	UHS-I, U3, V30, A1
Seq Read/Write	Up to 90/45MB/s
Dimensions(LxWxH)	15.0x11.0x1.0 mm
Operating Temp.	0°C~70°C
Storage Temp.	-40°C~85°C
Protection Level	Waterproof (IPX8), heat-resistant, impact resistant, and X-ray resistant (compliant with IEC/EN 529 standards)
Application Performance Level	A1 (2,000/500 IOPS)
Warranty	8-year limited warranty

Applications



Smartphones



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